

CLAIMS

1. A resin-coated copper foil, wherein the resin-coated copper foil has the resin layer on one surface of the copper foil, wherein the resin layer has a resin composition as follows:

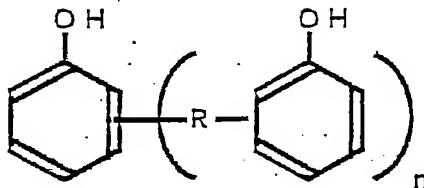
5 (1) 20 to 70 parts by weight of an epoxy resin

(2) 5 to 30 parts by weight of a high polymer having a crosslinkable functional group in its molecule and a crosslinking agent therefor in combination

(3) 10 to 60 parts by weight of a compound having a structure shown in

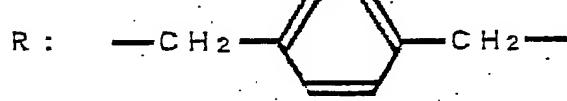
10 Formula 1:

Formula 1

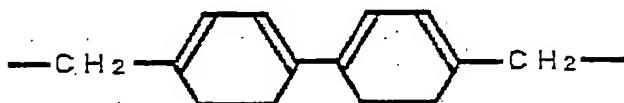


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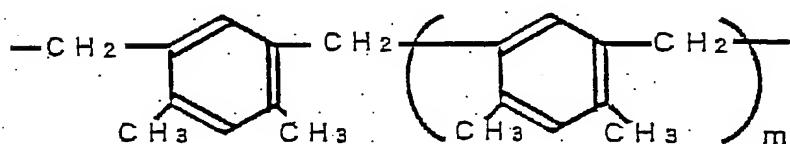
, wherein n is an integer of one or more,



or



or



, wherein m is an integer of 0 or greater.

2. The resin-coated copper foil according to claim 1, wherein the high polymer having a crosslinkable functional group in its molecule and the crosslinking agent therefor are one or more selected from the group consisting of a polyvinyl acetal resin, a phenoxy resin, a polyethersulfone resin, a carboxyl modified acrylonitrile-butadiene resin and an aromatic polyamide resin polymer, which are all soluble in a solvent.
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3. A multilayer printed wiring board, comprising the resin-coated copper foil according to claim 1 or 2.